

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00732	1.27	0.11176
	Doped silicon	Silicon (Si)	7440-21-3	0.56925	98.73	8.68824
Subtotal				0.57657	100	8.8
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.00771	5.0	0.11761
	Silver alloy	Silver (Ag)	7440-22-4	0.00231	1.5	0.03528
	Lead alloy	Lead (Pb)	7439-92-1	0.1441	93.5	2.19934
Subtotal				0.15412	100	2.35223
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.26211	100.0	4.00047
	Subtotal			0.26211	100	4.00047
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01289	0.04	0.1968
	Copper alloy	Iron (Fe)	7439-89-6	0.03223	0.1	0.49199
	Copper alloy	Copper (Cu)	7440-50-8	32.18982	99.86	491.30121
Subtotal				32.23494	100	491.99
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.35494	100.0	20.68
	Subtotal			1.35494	100	20.68
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.23338	8.0	79.8752
	Filler	Silica fused	60676-86-0	52.98802	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.45792	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19625	0.3	2.99532
	Polymer	Epoxy resin system		6.54173	10.0	99.844
Subtotal				65.4173	100	998.44
Total				99.99998	100	1526.2627

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